

2.5 W/mK + electrically conductive

A silver-filled, electrically conductive, low outgassing epoxy, Appli-Tec's 5200 is specifically designed to cure with low shrinkage at room temperature or cure quickly at elevated temperatures. The material is ideal for applications such as **electrical bonding, EMI shielding, and room temperature soldering**. 5200 exhibits a high thermal conductivity of 2.5 W/mK and a low volume resistivity of 0.002 ohm-cm, delivering excellent thermal and electrical conductivity across the bond line. Appli-Tec 5200 silver epoxy is available in bulk kits or two-part mixer pouches that can be stored at room temperature and mixed on site. We can also pre-mix, test, pre-pack and then flash freeze the material in manual or pneumatic dispense syringes, which are easily thawed at room temperature. The material is listed on NASA's Low Outgassing website.

UNCURED	
Pot Life @ 25°C	30 minutes
Viscosity Part A @ 25°C	Paste
Viscosity Part B @ 25°C	25 cPs
Shelf Life @ -40°C	6 Months
Shelf Life @ -60°C	10 Months
Shelf Life @ -75°C	24 Months
Shelf Life @ 25°C	6 Months (Appli-Pac®, Bulk Kit)
Mix Ratio	100A:4.31B Parts By Weight
CURE OPTIONS	2 hours @ 65°C 24 hours @ 25°C 30 minutes @ 100°C
CURED PROPERTIES	Based on cure of 2 hours @ 65°C
Color	Silver
Shore D Hardness	90
Glass Transition Temp (°C)	85
Specific Gravity	2.75
Lap Shear 2024T3 Clad (psi)	1,200
ELECTRICAL PROPERTIES	Based on cure of 2 hours @ 65°C
Volume Resistivity (ohm-cm)	2.0E-3
THERMAL PROPERTIES	Based on cure of 2 hours @ 65°C
Glass Transition Temp (°C)	85
Operating Temp. Range (°C)	-60 to 120
Thermal Conductivity (W/mK)	2.5
Degradation Temp. (°C)	300
OUTGASSING PROPERTIES	Based on cure of 2 hours @ 65°C
TML (%)	0.19
CVCM (%)	0.00
WVR (%)	0.17

KEY FEATURES

High Electrical Conductivity

Listed on NASA Low Outgassing Website

Low Shrinkage

Room Temperature Cure

Chat with a specialist:

service@appli-tec.com

603-685-0500 ext. 526

www.appli-tec.com

7 Industrial Way, Unit 1, Salem, NH 03079

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Rev K

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